SUSS MICROTEC INVESTOR PRESENTATION

September 2017

SUSS MICROTEC AT A GLANCE

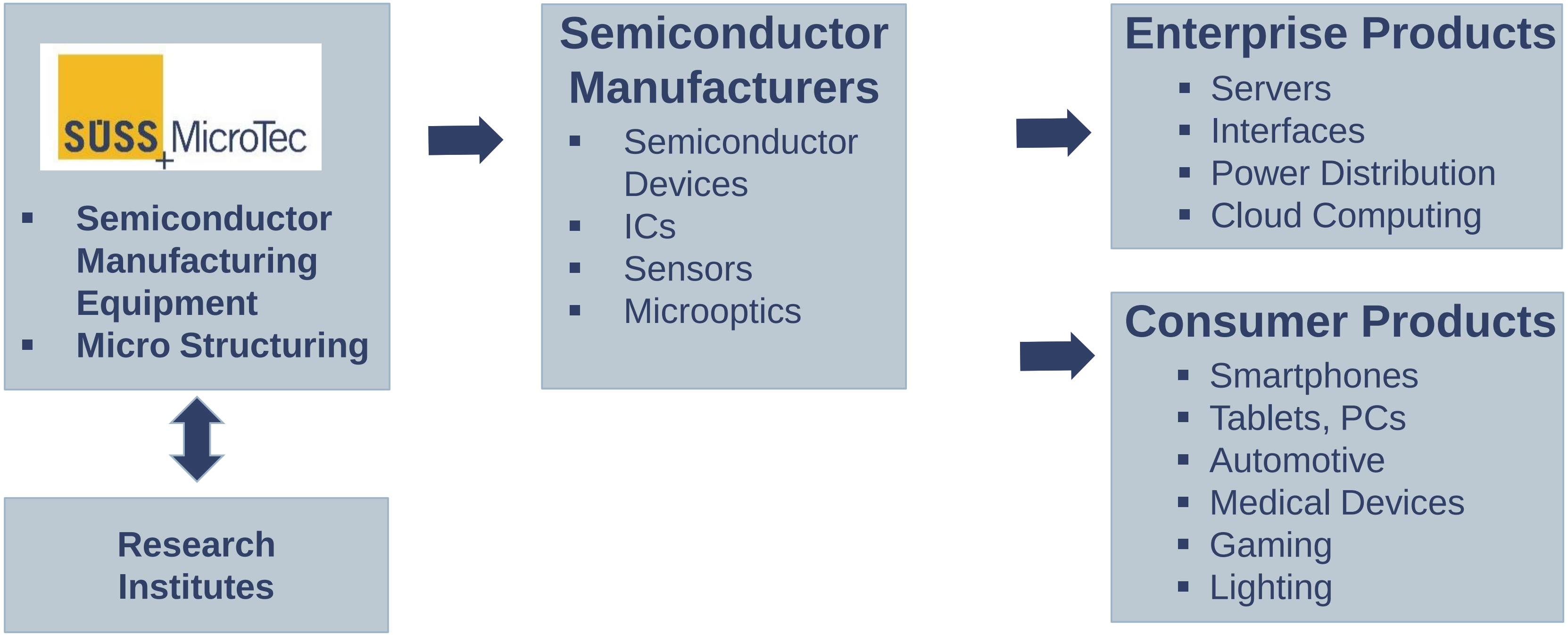
- International high tech equipment provider for the semiconductor industry
- All major chip manufacturers are clients of ours
- Global customer base with focus on Asian/Pacific
- Production an two major sites on Germany and on in the USA

Germany

USA

Mask Cleaning Equipment: MaskTrack PRO

SUSS MICROTEC IN THE VALUE CHAIN



- **Semiconductor Manufacturing Equipment**
- **Micro Structuring**

Research Institutes

Semiconductor Manufacturers

- Semiconductor Devices
- ICs
- Sensors
- Microoptics

Enterprise Products

- Servers
- Interfaces
- Power Distribution
- Cloud Computing

Consumer Products

- Smartphones
- Tablets, PCs
- Automotive
- Medical Devices
- Gaming
- Lighting

+ **SUSS MicroTec:**
  - Key player in leading edge semiconductor manufacturing equipment
  - Developer of highly innovative process solutions

+ Key components for electronic devices such as cell phones, PCs and tablet computers are produced with SUSS MicroTec’s equipment

SUSS MICROTEC – A GLOBAL PLAYER

NORTH AMERICA	EMEA	ASIA
Order Entry 33.7 € million	Order Entry 38.1 € million	Order Entry 89.3 € million
Sales 25.4 € million	Sales 43.1 € million	Sales 109.0 € million
Employees 102	Employees 469	Employees 140

■ Headquarters
▨ Production
□ Sales

□ ▨ Corona, US

■ ▨ Garching, DE
▨ Sternenfels, DE
▨ Hauterive, CH
□ Lyon, FR
□ Market Rasen, UK

□ Singapore, SG

□ Yokohama, JP
□ Hwaseong City, KR
□ Shanghai, CN
□ HsinChu, TW

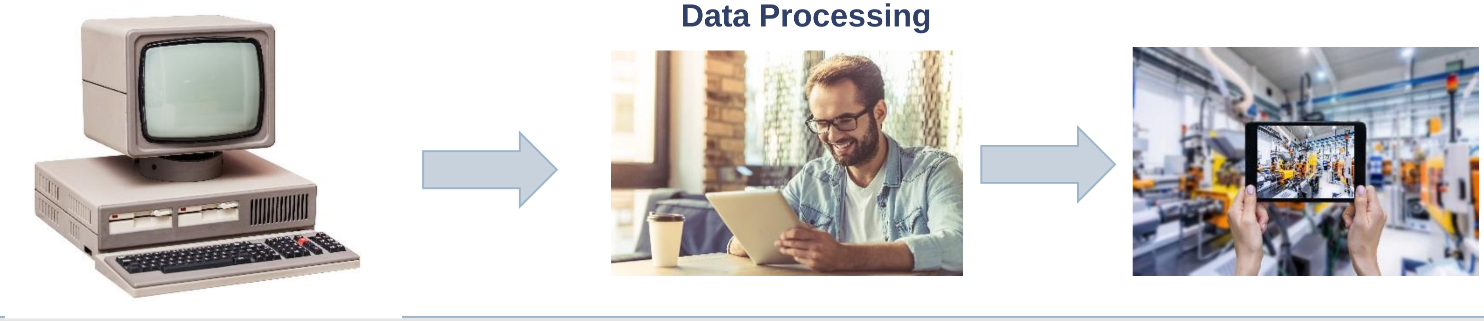
*Figures refer to the fiscal year 2016

WE SUPPORT TECHNOLOGICAL CHANGE

Telecommunication

- Communication
- Mobility
- Networks

Data Processing



- Data processing
- Mobility
- Digitalization
- Smart factory

Automotive

- Safety
- Comfort
- Energy efficiency
- Autonomous driving

Source: istock

CHANGES IN TELECOMMUNICATION

since 1980s
(radiotelephones)

Since 1990s
(cellphones)

Today
(smartphones)

- In the 1990s cellphones used to be large and heavy – today they are small and handy
- Shift from pure telephone functionality to minicomputer with many functions
- Video conferences, camera, navigation, internet access, electronic payment and many more
- Sensors for gravity, acceleration, rotation, pressure
- Countless APPs for many different applications
- Modern packaging technologies -> number of electronic components rises constantly
- 55% of all German citizen own a smartphone, 8% don’t have a cellphone (Source: Bitkom)

Source: istock

CHANGES IN DATA PROCESSING

1970/80s
(personal computer)

Since 2010
(tablets)

Future
(unlimited networking)

- **Computers are getting smaller, more powerful and mobile -> laptop -> tablet**
- **Computing power of a modern tablet >> mainframe of the moon mission Apollo 11 (1969)**
- **Almost unlimited mobility, communication and networking**
- **Thanks to progress in broadband networks: data volume rises continuously**
- **Nowadays items start to communicate with one other: “internet of things”**
- **Industry gets digitized, meaning that large amounts of data can be use for process optimization -> smart factory**

Source: istock

CHANGE IN SENSORS AND ACTUATORS

1980s
(first airbags)

1989
(navigation)

Future
(autonomous driving)

- **Sensors are the senses of a computer: connection to the outside world happens via sensors**
- **Example Car:**
  - **Sensor controlled electronics in cars improve comfort and safety**
  - **Engine control for reduced fuel consumption and lower emissions are not possible without sensors**
  - **In the future: autonomous driving for more flexibility, energy efficiency and safety**
- **Applications for sensors are in the computer and automotive industry, medical applications, security systems, internet of things and smart factory**
- **Number of MEMS sensors have been risen rapidly for years now**

Source: istock

GROWTH DRIVERS ARE INTACT

networks

internet of things

smart factory

mobility

digitization

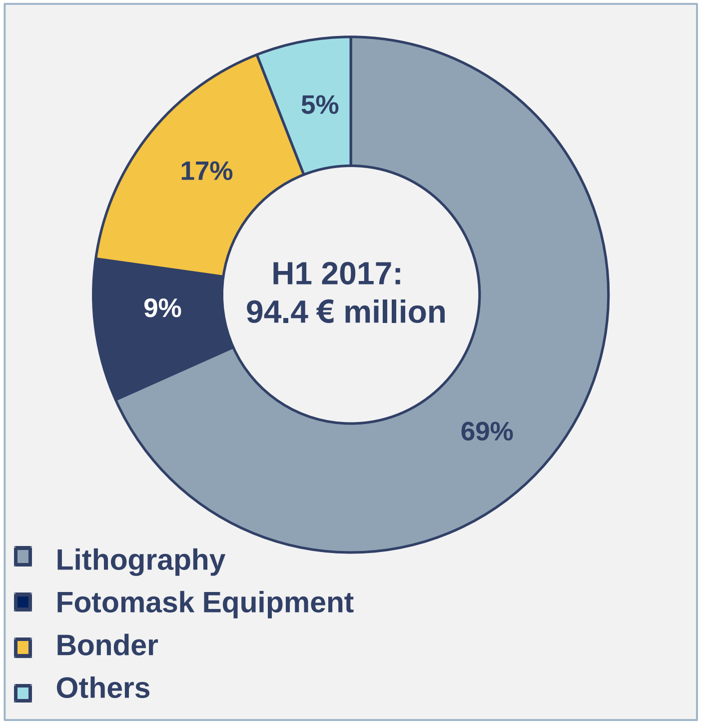
automation

communication

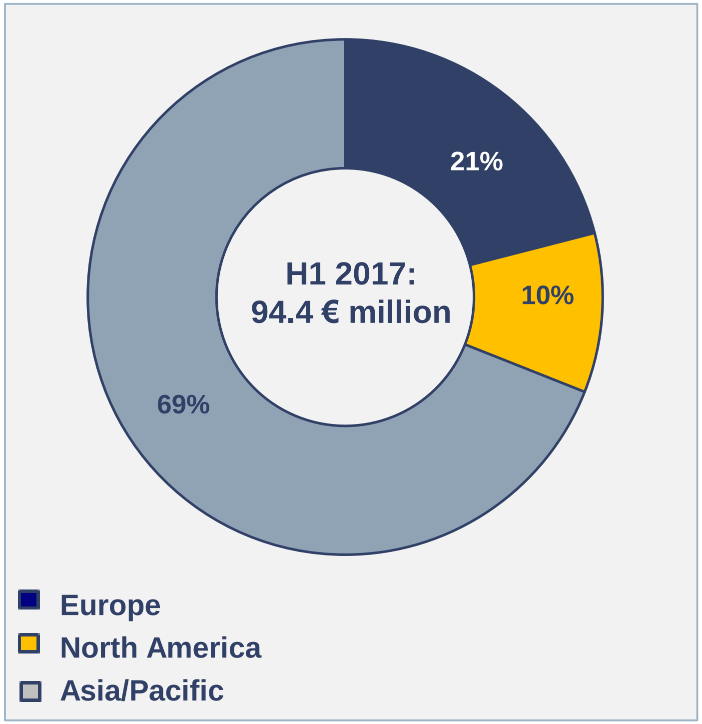
autonomous driving

ORDER ENTRY BY SEGMENT AND REGION IN H1 2017

Segments



Regions



SEGMENTS, ORDER ENTRY AND SALES FY 2016

Divisions

	Photomask Equipment	Lithography	Bonder
	Photomask Cleaning Equipment	Laser Processing Equipment Exposure Systems Coaters and Developers	Wafer Bonding Equipment
FY 2016	**Order Entry: 26.3 € million** **Sales: 19.7 € million** **EBIT: 1.8 € million**	**Order Entry: 105.0 € million** **Sales: 133.8 € million** **EBIT: 13.2 € million**	**Order Entry: 18.6 € million** **Sales: 14.0 € million** **EBIT: -1.7 € million**

SUSS MicroTec Group* FY 2016

Order Entry: 161.1 € million
Sales: 177.6 € million
EBIT: 11.1 € million
EBIT margin: 6.3%

* Including Others

SEGMENTS, ORDER ENTRY AND SALES H1 2017

Divisions

Photomask Equipment

Photomask Cleaning Equipment

H1 2017

Order Entry: 8.1 € million
Sales: 9.8 € million
EBIT: 1.8 € million

Lithography

Laser Processing Equipment

Exposure Systems

Coaters and Developers

Order Entry: 64.7 € million
Sales: 43.7 € million
EBIT: 0.1 € million

Bonder

Wafer Bonding Equipment

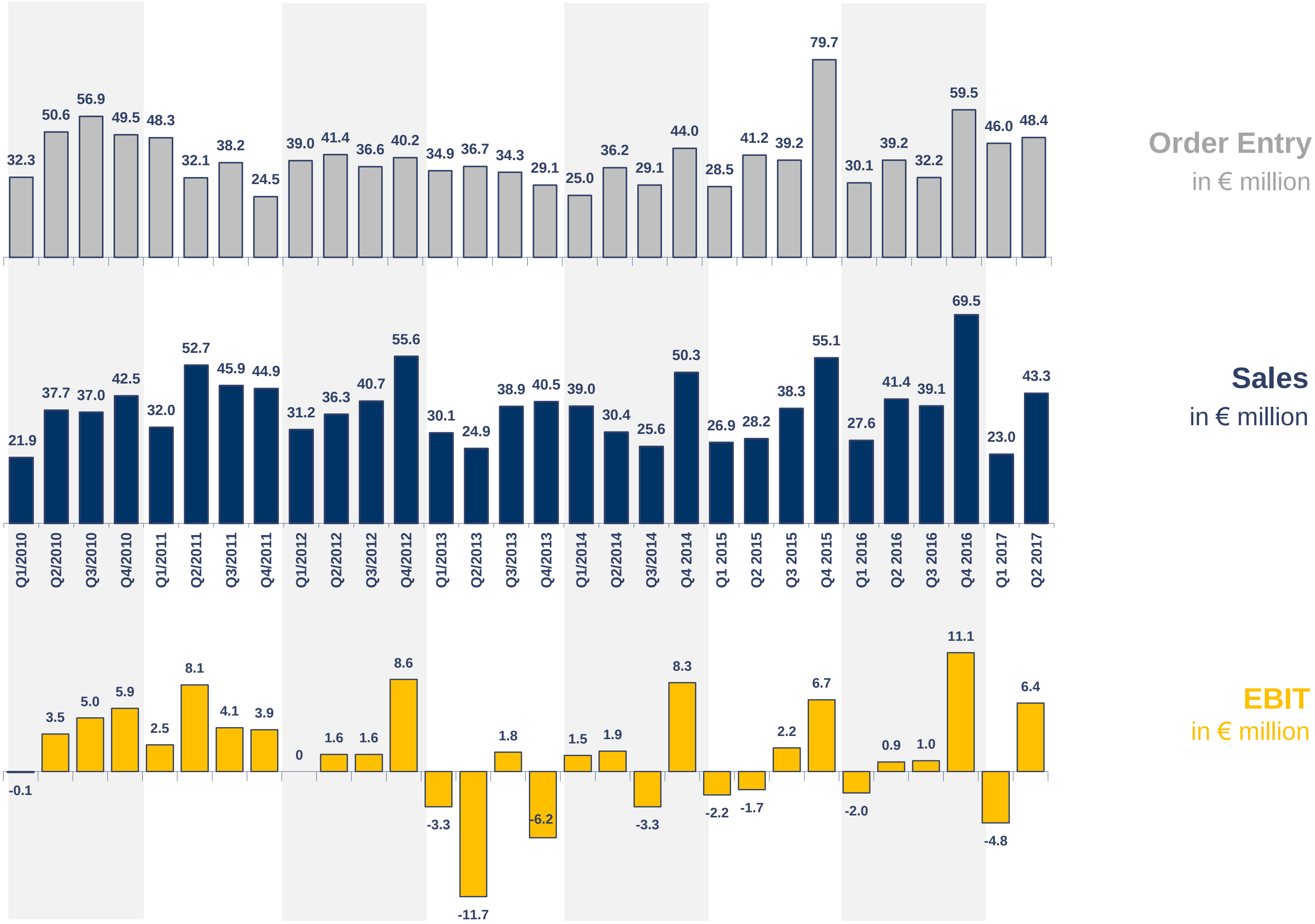
Order Entry: 15.6 € million
Sales: 7.3 € million
EBIT: 0.5 € million

SUSS MicroTec Group* H1 2017

Order Entry: 94.4 € million
Sales: 66.3 € million
EBIT: 1.6 € million
EBIT margin: 2.3%

* Including Others

LONG TERM BUSINESS DEVELOPMENT BY QUARTER



DRIVERS FOR FOWLP AND 3D TSV TECHNOLOGIES

Portable electronic products are driving component packaging towards new packaging technologies for integrating multiple functions (e.g. memory, analog and passive components: SiP)

Fan Out Wafer Level Packaging	**(FOWLP)**
Three Dimensional Through Silicon Via	**(3D TSV)**

Allows for:

- + **Smaller form factors**
- + **Multi-die package / SiP**
- + **Increased I/O density** (Fine line and space (L/S))
- + **Providing high capacity and high bandwidth packages**

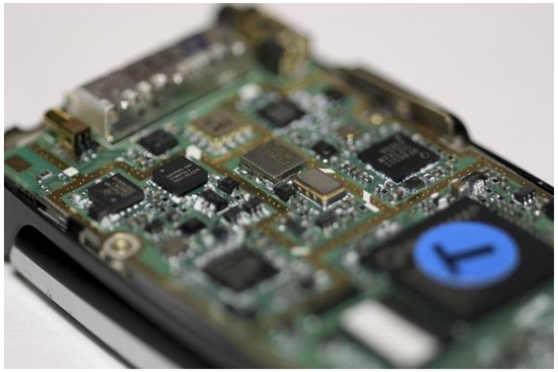
→ **Trend will continue**

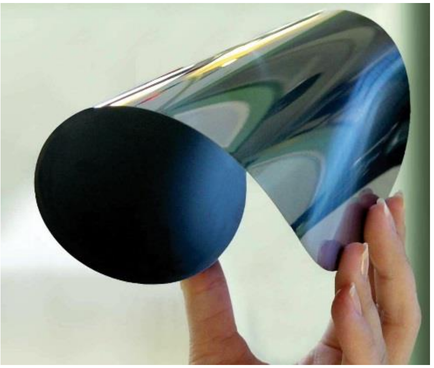
3D-TSV-INTEGRATION GAINS PACE

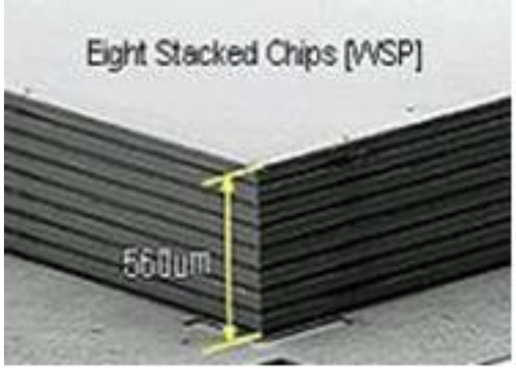
- Since the early 1990s, advanced packaging methods have enabled smaller chip packages
  - SUSS was one of the drivers in the introduction of advanced packaging in the 1990s
  - SUSS was a founding member of SECAP (Semiconductor Equipment Consortium for Advanced Packaging)
  - SECAP supported the transition from "wire bonding" to "flip chip bonding“

- Today, SUSS supports the transition from 2D to 2.5D and finally to 3D TSV (Thru Silicon Via)
  - SUSS works with the leading users of the 3D TSV technology
  - The first pilot lines are already installed and will be further optimized
  - SUSS is one of the leading equipment suppliers for this growth area

- „Thin wafer handling “ und „temporary bonding“ are major elements of 3D stacking



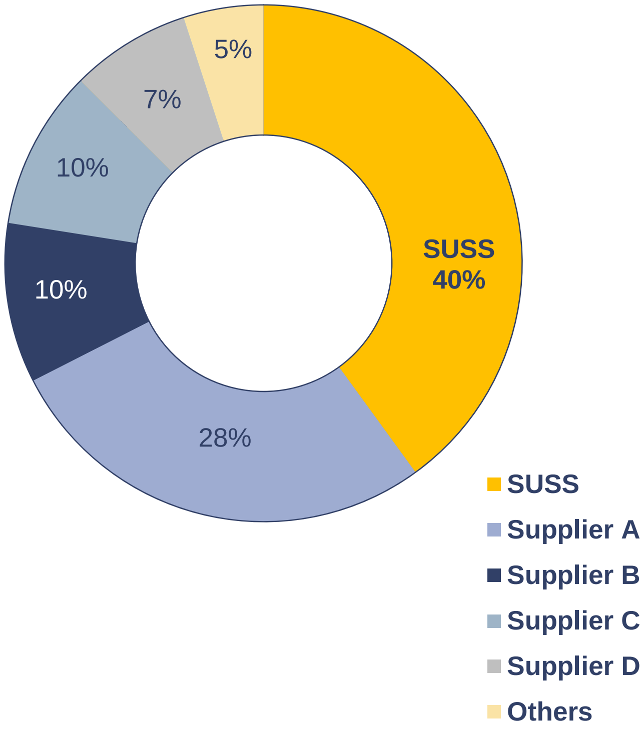




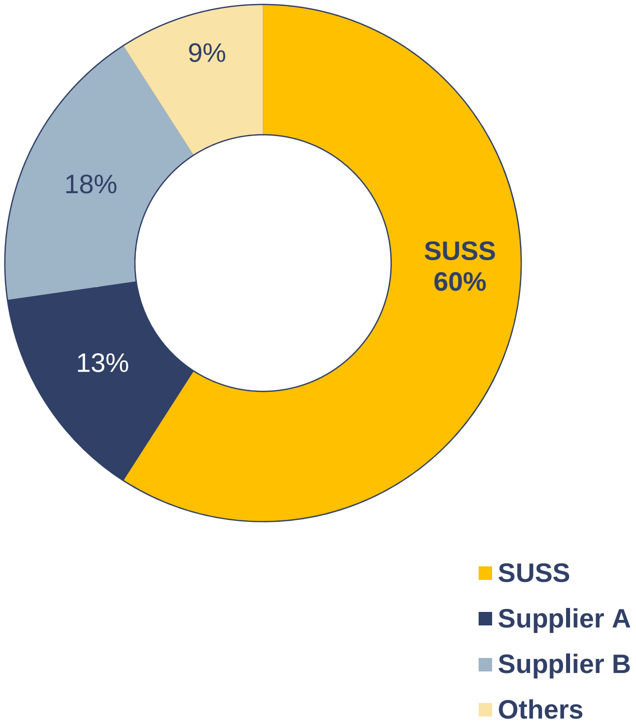
Source: istock, Samsung

WORLD-WIDE MARKET SHARE TBDB AUTO EQUIPMENT

TBDB Auto Tool Market Share 2017 for 2.5D and 3D TSV

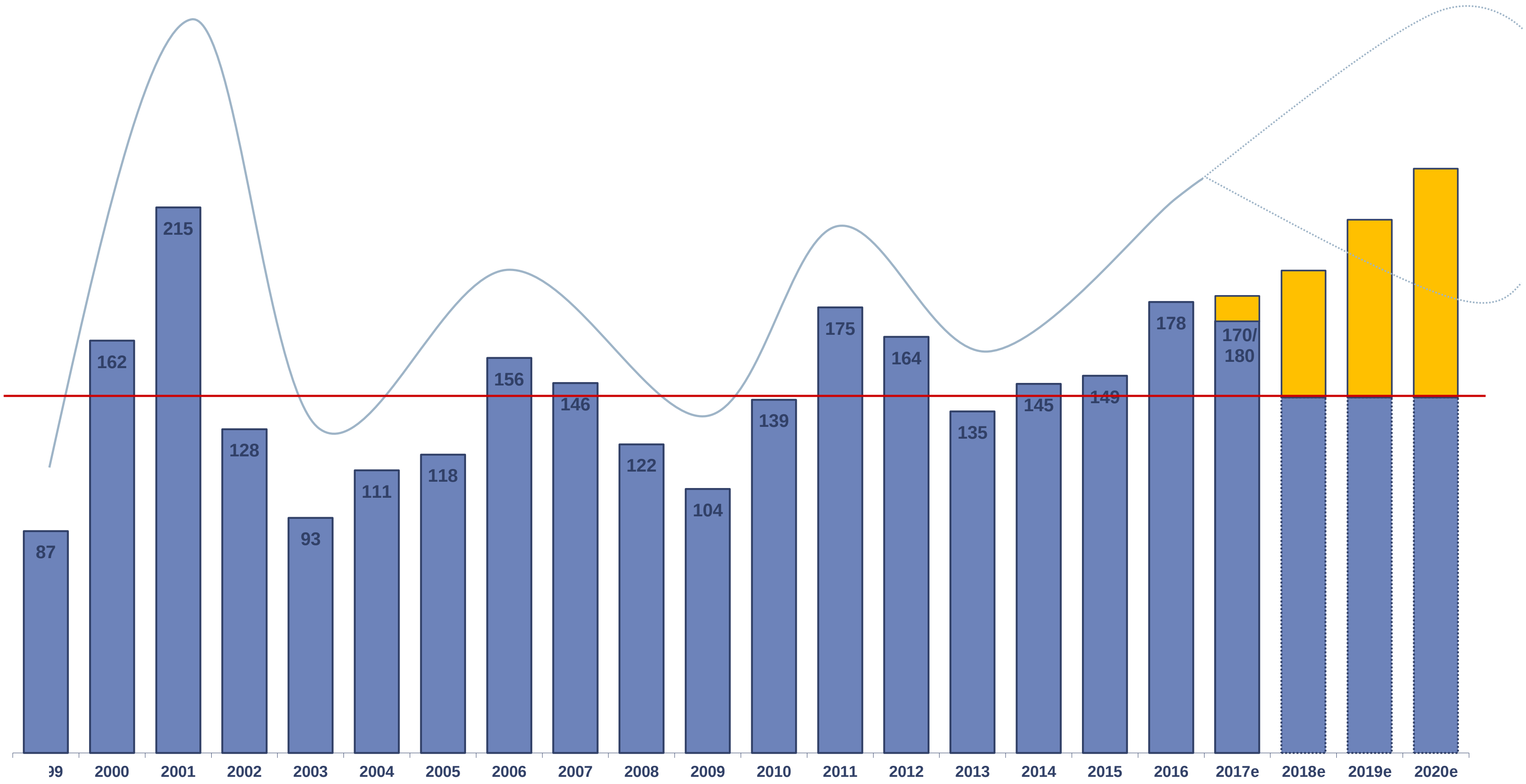


TBDB Auto Tool Market Share 2017 Top 3 IDMs – 3D TSV based memory



→ **SUSS is the #1 equipment supplier for TBDB auto equipment for 2.5D, 3D and WLP applications**

LONG TERM SALES DEVELOPMENT IN MIO. €



Average sales level 1999 – 2016: appr. € 140 million

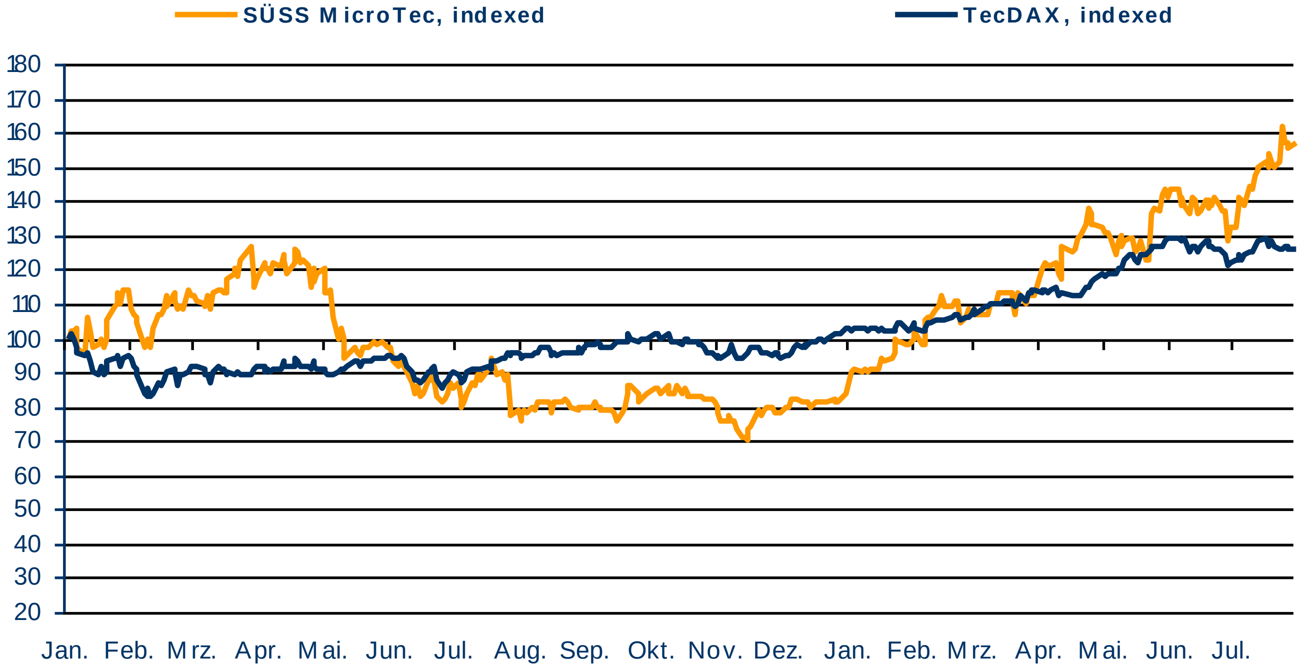
KEY GROUP FIGURES AT A GLANCE

in € million	Q2 2017	Q2 2016	in %	*H1 2017*	*H1 2016*
Order Intake	48.4	39.2	+23.5%	*94.4*	*69.3*
Order Backlog 6/30	--	--	--	*128.8*	*117.7*
Revenue	43.3	41.4	+4.6%	*66.3*	*69.0*
EBIT	6.4	0.9	>100%	*1.6*	*-1.0*
EBIT in % of Sales	*14.8%*	*2.2%*	>100%	*2.4%*	*-1.4%*
Earnings after tax	3.9	-0.6	>100%	*-0.7*	*-3.1*
EPS in €	0.20	-0.03	>100%	*-0.04*	*-0.16*
Free Cash Flow*	-1.7	0.9	<100%	*-5.6*	*-12.0*
Net Cash	--	--	--	*25.0*	*28.1*
Employees 6/30	--	--	--	*734*	*717*

*before consideration of transactions with interest-bearing securities

SHARE PRICE DEVELOPMENT AND MAJOR HOLDERS

(Price of the SUSS MicroTec Share at January 2, 2016: 4.88 €)

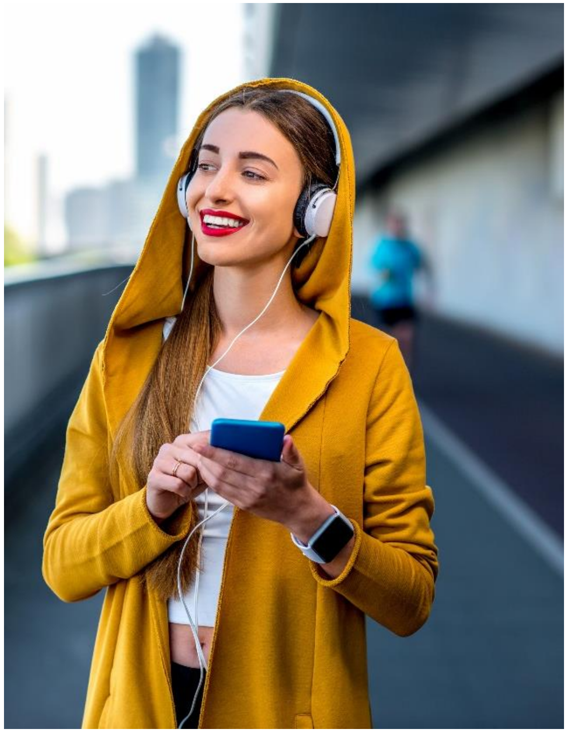


Major Shareholders:

Henderson	5.1%
Universal	5.1%
Sycomore	4.7%
Luxempart	3.5%
Lupus Alpha	3.2%
Dimensional	3.0%

Average daily trading volume January 2016 – September 2017: ~ 150.000

MARKET OUTLOOK 2017



- Gartner increased its expectations for growth in the semiconductor segment from +7.2% to +12.3% in 2017
- This would mark a new record sales level of USD 386 billion for the semiconductor industry
- Market growth is driven by automotive and industrial applications as well as memory chips and the internet of things
- Semi expects a market growth of the semiconductor-equipment industry in 2017 of +19,8%
- Wafer-level packaging and assembly will grow by +12,8% in 2017 after +3.9% in 2016 (according to Semi)
- Yole expects the MEMS-market to grow by +12% (CAGR) from 2016 to 2021(unit growth)

OUTLOOK 2017

- Fiscal year 2017: Sales € 170 to 180 million
  EBIT € 15 to 19 million
- 3rd quarter 2017: Order entry € 35 to 45 million

WE ARE SUSS MICROTEC

INVESTOR RELATIONS INFORMATION

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Financial Calendar 2017

Annual Report 2016	30 Mar
Quarterly Report 2017	4 May
Annual General Meeting 2017, Munich	31 May
Interim Report 2017	10 Aug
Nine-month Report 2017	9 Nov

DISCLAIMER

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